

WHAT IS CLAIMED IS:

An image sensor module, comprising:

an image sensor package formed with a top end face having a transparent layer and a bottom end face ;

5 a lens holder formed with a chamber, which has an internal thread formed at the inner wall, so that the transparent layer of the image sensor package is arranged at the lens holder ;

a lens barrel inserted within the chamber of the lens holder, and formed with an external thread, which is screwed on the internal thread of the lens holder, the
10 lens barrel being formed with an opening and a hole communicating the opening, which is formed with a first positioned slot for positioning an aspheric lens.

2.The image sensor module according to claim 1, wherein the lens barrel is formed with a second positioned slot under the first positioned slot for positioning an infrared filter.

15 3. The image sensor module according to claim 1, wherein the image sensor package includes a substrate, a frame arranged on the substrate, a photosensitive chip arranged on the substrate and electrically connected to the substrate by wires, and a transparent layer mounted on the frame layer.

4. The image sensor module according to claim 1, wherein the transparent layer
20 is an infrared filter.

5. A method for manufacturing an image sensor module, comprising the steps of :

providing an image sensor package formed with a top end face having a transparent layer and a bottom end face ;

5 providing a lens holder formed with a chamber, which has an internal thread formed at the inner wall, so that the transparent layer of the image sensor package is arranged at the lens holder ;

providing a lens barrel inserted within the chamber of the lens holder, and formed with an external thread, which is screwed on the internal thread of the
10 lens holder, the lens barrel being formed with an opening and a hole communicating the opening, which is formed with a first positioned slot for positioning an aspheric lens, the lens barrel and the aspheric being integrated formed by injecting molded.

7.The method according to claim 6, wherein lens barrel is formed with a second
15 positioned slot under the first positioned slot for positioning an infrared filter.

8.The method according to claim 6, wherein the image sensor package includes a substrate, a frame arranged on the substrate, a photosensitive chip arranged on the substrate and electrically connected to the substrate by wires, and a transparent layer mounted on the frame layer.